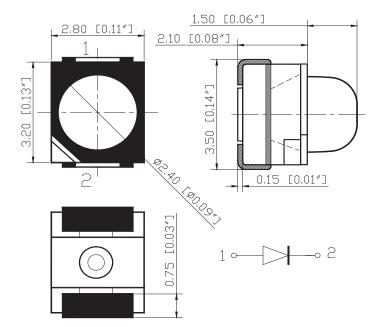
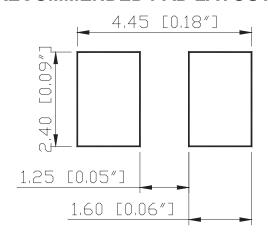


SPECIFICATION CSD1311GT2C-B

PACKAGE OUTLINES



RECOMMENDED PAD LAYOUT



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

| Part Number | Part Number Chip Material | | Lens Type | Viewing Angle | |
|---------------|---------------------------|-------|-------------|---------------|--|
| CSD1311GT2C-B | InGaN | Green | Water Clear | 30° | |





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

| Parameter | Symbol | Max Rating | Unit | |
|--|--------|-------------------------|------|--|
| Forward Current | lF | 30 | mA | |
| Reverse Current @ 5V | lr | 10 | μA | |
| Power Dissipation | Pd | 111 | mW | |
| Operating Temperature Range | Тор | -40~+80 | °C | |
| Storage Temperature Range | Тѕтс | -40~+85 | °C | |
| Peak Pulsing Current (1/10 duty f = 10KHz) | lfp | 125 | mA | |
| Soldering Temperature | TsoL | Max 260°C for 10 sec Ma | | |

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

| Darameter | Symbol | Toot Condition | Value | | | Lloit |
|-------------------------|------------|---------------------|-------|-------|-----|-------|
| Parameter | | Test Condition | Min | Тур | Max | Unit |
| Luminous Intensity | lv | IF = 20mA | 6800 | 11500 | 1 | mcd |
| Forward Voltage | VF | IF = 20mA | - | 3.2 | 3.7 | V |
| Reverse Leakage Current | lr | V _R = 5V | - | 10 | ı | μΑ |
| Viewing Angle at 50% Iv | 201/2 | IF = 20mA | - | 30 | ı | Deg |
| Peak Wavelength | λ P | IF = 20mA | - | 520 | - | nm |
| Dominant Wavelength | λ D | IF = 20mA | 520 | 525 | 530 | nm |

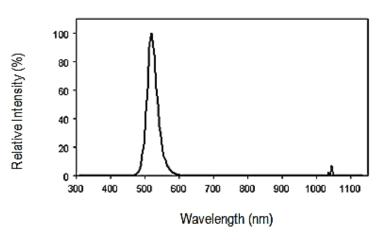
^{*}Tolerance of viewing angle: -10 / +5 deg.



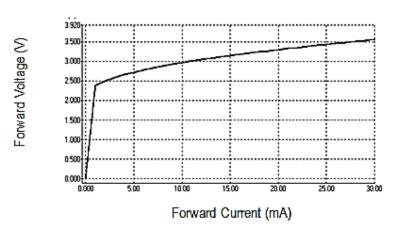


OPTICAL CHARACTERISTIC CURVES

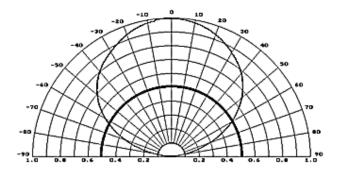
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics



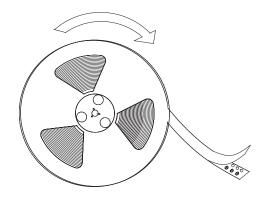




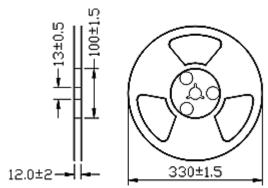
PACKAGING SPECIFICATION

PACKAGE SPECIFICATIONS

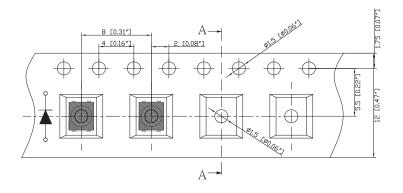
Feeding Direction

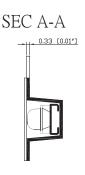


Dimensions of Reel (Unit: mm)

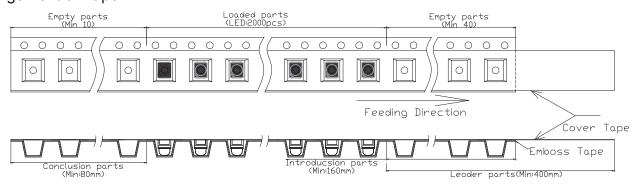


Dimensions of Tape (Unit: mm)





Arrangement of Tape



Notes:

- 1. Empty component pockets are sealed with top cover tape.
- 2. The maximum number of missing lamp is two.
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 2,000 pcs/Reel

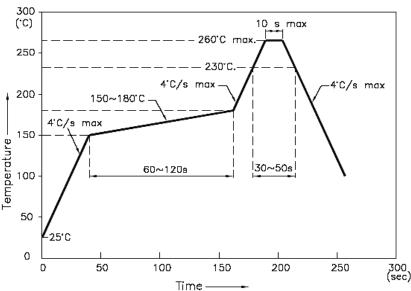




SOLDERING CONDITIONS

REFLOW PROFILE

Reflow Temp/Time



Notes:

- 1. We recommend the reflow temperature 245°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.
- Soldering Iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

- Rework
- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil.
- 3. Twin-head type is preferred.

